

Enric Cabruja

List of Publications by Year in descending order

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73
papers

3,143
citations

430874

18
h-index

197818

49
g-index

73
all docs

73
docs citations

73
times ranked

5791
citing authors

#	ARTICLE	IF	CITATIONS
1	Use of accelerometer technology for individual tracking of activity patterns, metabolic rates and welfare in farmed gilthead sea bream (<i>Sparus aurata</i>) facing a wide range of stressors. <i>Aquaculture</i> , 2021, 539, 736609.	3.5	11
2	SU-8 processing improvement and simulating studies for a Micromegas detector fabrication. <i>Journal of Instrumentation</i> , 2021, 16, P08022.	1.2	0
3	From operculum and body tail movements to different coupling of physical activity and respiratory frequency in farmed gilthead sea bream and European sea bass. <i>Insights on aquaculture biosensing. Computers and Electronics in Agriculture</i> , 2020, 175, 105531.	7.7	14
4	Ultra-Low Power Sensor Devices for Monitoring Physical Activity and Respiratory Frequency in Farmed Fish. <i>Frontiers in Physiology</i> , 2019, 10, 667.	2.8	32
5	3D Printed porous polyamide macrocapsule combined with alginate microcapsules for safer cell-based therapies. <i>Scientific Reports</i> , 2018, 8, 8512.	3.3	25
6	Pixel CdTe semiconductor module to implement a sub-MeV imaging detector for astrophysics. <i>Journal of Instrumentation</i> , 2017, 12, C03048-C03048.	1.2	4
7	Development of a pixelated CdTe detector module for a hard-x and gamma-ray imaging spectrometer application. , 2016, , .		0
8	Hard-X and gamma-ray imaging detector for astrophysics based on pixelated CdTe semiconductors. <i>Journal of Instrumentation</i> , 2016, 11, C01011-C01011.	1.2	2
9	Measurement of mobility and lifetime of electrons and holes in a Schottky CdTe diode. <i>Journal of Instrumentation</i> , 2014, 9, C12032-C12032.	1.2	20
10	Simulation of the Expected Performance of a Seamless Scanner for Brain PET Based on Highly Pixelated CdTe Detectors. <i>IEEE Transactions on Medical Imaging</i> , 2014, 33, 332-339.	8.9	18
11	A 10kfps 32×32 integrated test platform for electrical characterization of imagers. , 2014, , .		0
12	Characterization of a module with pixelated CdTe detectors for possible PET, PEM and compton camera applications. <i>Journal of Instrumentation</i> , 2014, 9, C05046-C05046.	1.2	2
13	3D double sided detector fabrication at IMB-CNM. <i>Nuclear Instruments and Methods in Physics Research, Section A: Accelerators, Spectrometers, Detectors and Associated Equipment</i> , 2013, 699, 27-30.	1.6	37
14	Energy and coincidence time resolution measurements of CdTe detectors for PET. <i>Journal of Instrumentation</i> , 2013, 8, C02015-C02015.	1.2	18
15	Development and performance of a gamma-ray imaging detector. <i>Proceedings of SPIE</i> , 2012, , .	0.8	3
16	Integrated design of a smart analog sun sensor with CMOS technology. , 2012, , .		0
17	Charged particle tracking with the Timepix ASIC. <i>Nuclear Instruments and Methods in Physics Research, Section A: Accelerators, Spectrometers, Detectors and Associated Equipment</i> , 2012, 661, 31-49.	1.6	50
18	Electromagnetic harvester device for scavenging ambient mechanical energy with slow, variable, and randomness nature. , 2011, , .		2

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19	Characterization of CdTe detector for use in PET. , 2011, , .		7
20	Modeling, simulation, and evaluation of a compton camera based on a pixelated solid-state detector. , 2011, , .		9
21	Simulation of pseudo-clinical conditions and image quality evaluation of PET scanner based on pixelated CdTe detector. , 2011, , .		10
22	Research and development of a gamma-ray imaging spectrometer in the MeV range in Barcelona. , 2010, , .		4
23	Infrared-transparent microstrip detectors. Nuclear Instruments and Methods in Physics Research, Section A: Accelerators, Spectrometers, Detectors and Associated Equipment, 2009, 598, 84-85.	1.6	0
24	Fabrication and simulation of novel ultra-thin 3D silicon detectors. Nuclear Instruments and Methods in Physics Research, Section A: Accelerators, Spectrometers, Detectors and Associated Equipment, 2009, 604, 115-118.	1.6	15
25	Early determination of cystic fibrosis by electrochemical chloride quantification in sweat. Biosensors and Bioelectronics, 2009, 24, 1788-1791.	10.1	92
26	Cross-Section Preparation for Solder Joints and MEMS Device Using Argon Ion Beam Milling. IEEE Transactions on Electronics Packaging Manufacturing, 2009, 32, 265-271.	1.4	17
27	Thin-Film Bulk Acoustic Wave Resonator Floating Above CMOS Substrate. IEEE Electron Device Letters, 2008, 29, 28-30.	3.9	9
28	The ATLAS Experiment at the CERN Large Hadron Collider. Journal of Instrumentation, 2008, 3, S08003-S08003.	1.2	1,752
29	Carbon nanotube/polysulfone composite screen-printed electrochemical enzyme biosensors. Analyst, The, 2007, 132, 142-147.	3.5	78
30	Special bump bonding technique for silicon pixel detectors. Nuclear Instruments and Methods in Physics Research, Section A: Accelerators, Spectrometers, Detectors and Associated Equipment, 2007, 576, 150-153.	1.6	9
31	Ultra radiation hard silicon detectors for future experiments: 3D and p-type technologies. Nuclear Physics, Section B, Proceedings Supplements, 2007, 172, 17-19.	0.4	1
32	Bonding techniques for hybrid active pixel sensors (HAPS). Nuclear Instruments and Methods in Physics Research, Section A: Accelerators, Spectrometers, Detectors and Associated Equipment, 2007, 574, 392-400.	1.6	20
33	Characterisation of electroplated Sn/Ag solder bumps. Microelectronics Journal, 2006, 37, 308-316.	2.0	28
34	Flip-chip packaging of piezoresistive pressure sensors. Sensors and Actuators A: Physical, 2006, 132, 415-419.	4.1	19
35	High density of electrodeposited Sn/Ag bumps for flip chip connection. Microelectronic Engineering, 2006, 83, 399-403.	2.4	33
36	Review of CMOS image sensors. Microelectronics Journal, 2006, 37, 433-451.	2.0	445

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37	Test structure assembly for bump bond yield measurement on high density flip chip technologies. <i>Microelectronics Reliability</i> , 2006, 46, 1095-1100.	1.7	0
38	Characterization of thermal conductivity in thin film multilayered membranes. <i>Thin Solid Films</i> , 2005, 484, 328-333.	1.8	13
39	Piezoresistive accelerometers for MCM-package - Part II: The packaging. <i>Journal of Microelectromechanical Systems</i> , 2005, 14, 806-811.	2.5	11
40	Magnetic micro-transformers realized with a flip-chip process. <i>Journal of Micromechanics and Microengineering</i> , 2004, 14, S55-S58.	2.6	3
41	Feasibility of a flip-chip approach to integrate an IR filter and an IR detector in a future gas detection cell. <i>Microsystem Technologies</i> , 2004, 10, 382-386.	2.0	13
42	Laser stripe peak detector for 3D scanners. A FIR filter approach. , 2004, , .		71
43	Effect of Combined Oxygenation and Gettering on Minority Carrier Lifetime in High-Resistivity FZ Silicon. <i>Journal of the Electrochemical Society</i> , 2004, 151, G652.	2.9	3
44	Adapting MCM-D technology to a piezoresistive accelerometer packaging. <i>Journal of Micromechanics and Microengineering</i> , 2003, 13, S41-S44.	2.6	3
45	Extensive electrical and thermal characterization of an MCM-D technology. <i>IEEE Transactions on Components and Packaging Technologies</i> , 2002, 25, 112-119.	1.3	1
46	Piezoresistive accelerometers for MCM package. <i>Journal of Microelectromechanical Systems</i> , 2002, 11, 794-801.	2.5	41
47	Bump bonding of pixel systems. <i>Nuclear Instruments and Methods in Physics Research, Section A: Accelerators, Spectrometers, Detectors and Associated Equipment</i> , 2001, 473, 95-101.	1.6	16
48	Reliability evaluation of a silicon-on-silicon MCM-D package. <i>Microelectronics Reliability</i> , 2001, 41, 887-899.	1.7	3
49	Accurate contact resistivity extraction on Kelvin structures with upper and lower resistive layers. <i>IEEE Transactions on Electron Devices</i> , 2000, 47, 1431-1439.	3.0	18
50	Test structures for MCM-D technology characterization. <i>IEEE Transactions on Semiconductor Manufacturing</i> , 1999, 12, 184-192.	1.7	8
51	Peripheral nerve regeneration through microelectrode arrays based on silicon technology. <i>Restorative Neurology and Neuroscience</i> , 1996, 9, 151-160.	0.7	39
52	New technology for easy and fully IC-compatible fabrication of backside-contacted ISFETs. <i>Sensors and Actuators B: Chemical</i> , 1995, 24, 228-231.	7.8	12
53	Perforated silicon dices with integrated nerve guidance channels for interfacing peripheral nerves. , 1995, , .		8
54	Regenerative-type neural interface. <i>Lecture Notes in Computer Science</i> , 1995, , 114-120.	1.3	0

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55	Stress in low pressure chemical vapour deposition polycrystalline silicon thin films deposited below 0.1 Torr. Sensors and Actuators A: Physical, 1993, 37-38, 723-726.	4.1	13
56	Electrical characterization of MOS structures fabricated on SF6 and SF6 + C2ClF5 reactive ion etched silicon. Nuclear Instruments & Methods in Physics Research B, 1993, 80-81, 1362-1366.	1.4	0
57	Deep trenches in silicon using photoresist as a mask. Sensors and Actuators A: Physical, 1993, 37-38, 766-771.	4.1	8
58	A study of metal-oxide-semiconductor capacitors fabricated on SF6 and SF6+Cl2 reactive-ion-etched Si. Journal of Applied Physics, 1992, 71, 2710-2716.	2.5	7
59	Characterization of the Electrical Damage due to Polysilicon RIE (SF6+Cl2 Plasma) on the Electrochemical Society, 1992, 139, 193-195.	2.5	2
60	Influence of the degradation on the surface states and electrical characteristics of EOS structures. Surface Science, 1991, 251-252, 364-368.	1.9	11
61	Latch-up characterization using novel test structures and instruments. IEEE Transactions on Semiconductor Manufacturing, 1991, 4, 199-205.	1.7	2
62	Flow-through pH-ISFET as detector in automated determinations. Electroanalysis, 1991, 3, 349-354.	2.9	12
63	pH-ISFET with NMOS technology. Electroanalysis, 1991, 3, 355-360.	2.9	23
64	Flow of PECVD Oxide Films Doped with POCl3. Journal of the Electrochemical Society, 1991, 138, 181-183.	2.9	0
65	Positive photoresist stripping by plasma barrel. Vacuum, 1989, 39, 757-759.	3.5	1
66	Highly doped silicon microtubular electrodes for neural recording. , 0, , .		1
67	Test structures for MCM-D technology characterization. , 0, , .		1
68	Smart temperature sensor for on-line monitoring in automotive applications. , 0, , .		5
69	A MCM module for modern power window control in automotive applications. , 0, , .		5
70	PSK to ASK converter for RF digital communications. , 0, , .		1
71	A compact MCM implementation of an embedded system for automotive applications. , 0, , .		0
72	Feasibility of a flip chip approach to integrate an IR filter and an IR detector in a future gas detection cell. , 0, , .		0

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73	Thermal conductivity determination of micromachined membranes. , 0 , , .		2